122-46

SCREEN-PRINTABLE, B-STAGEABLE, EPOXY ADHESIVE

DESCRIPTION: 122-46 is a screen-printable, B-Stageable, one part epoxy coating and adhesive. This system features excellent thermal stability, outstanding chemical resistance and excellent high temperature properties. Applications include adhesives, printed circuit board fabrication, advanced material composites, sealing, and high performance coatings.

PROPERTIES:

- Viscosity (cps): 12,000-16,000
- Glass Transition Temp. (°C): 105
- Dielectric Strength (volts/mil.): 425
- Volume Resistivity (ohm-cm.): $1 \times 10^{16}$
- Dielectric Constant (100Hz): 4.0

SUGGESTED HANDLING AND CURING: Material is ready to use as received. Store frozen to maintain consistent flow properties. Allow material to warm up to room temperature before opening container. Prior to using mix container well.

STORAGE: Shelf Life -2 months at 25°C or 6 months at -10°C.

B-STAGE PROCEDURE: Apply adhesive to substrate. Next apply heat to advance the curing to the non-tacky stage (when cooled to room temperature). A temperature of 125°C for 2-3 minutes is required (B-Stage time is mass related). User is encouraged to experiment for optimum drying time at a given temperature. Store on release liner to prevent contamination.

STORAGE B-STAGED FILM: Shelf Life - 1 month @ 25°C; or 6 months @ -10°C

BONDING PROCEDURE: Refer to above for storage information. To use, carefully align parts to be bonded, apply uniform pressure to maintain location. Cure for 1.5-2 hours at 135°C. May also be cured for one hour at 150°C, or 45 minutes @ 165°C, or 30 minutes @175°C. (Note cure times given are mass related. Timing should start after adhesive and substrates reach curing temperature.)

SAFETY AND HANDLING: Use with adequate ventilation. Keep away from sparks and open flames. Avoid prolonged contact with skin and breathing of vapors. Wash with soap and water to remove from skin.

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to results or possible infringements on patents.

REVISION DATE: 2/17/04 REVISION: B